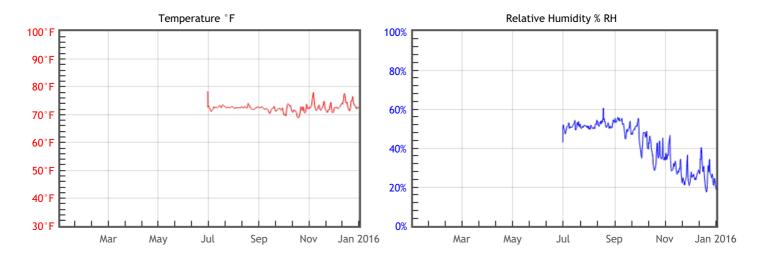
Ground East (EG1)

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	RISK TWPI = 37	Accelerated rate of chemical decay in all organic materials due to the cumulative effects of temperature and humidity, with especially high risk for fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics.
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 1.19 % EMC min = 5.5 % EMC max = 9.7	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 9.7	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs



Temperature		Relative Humidity		Dew Point	
T°F Mean	72.5	%RH Mean	42	DP°F Mean	46.8
T°F Median	72.4	%RH Median	47	DP°F Median	50.9
T°F Stdev	1.3	%RH Stdev	11	DP°F Stdev	8.2
T°F Min	68.8	%RH Min	15	DP°F Min	21.9
T°F Max	78.3	%RH Max	62	DP°F Max	60.4

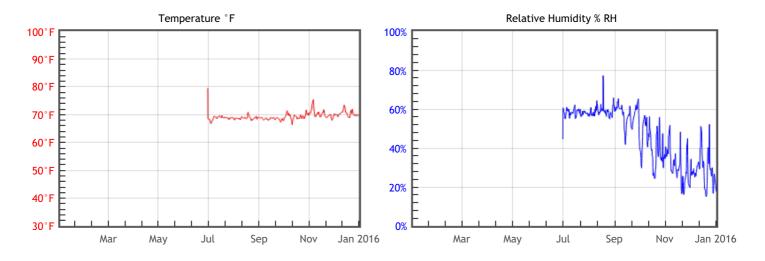
Ground West - East (WG16)

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	RISK TWPI = 40	Accelerated rate of chemical decay in all organic materials due to the cumulative effects of temperature and humidity, with especially high risk for fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics.
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 1.44 % EMC min = 5.8 % EMC max = 11	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0.01	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	RISK % EMC max = 11	Heightened risk of metal corrosion due to extended periods of high levels of humidity.

Graphs



Temperature		Relative Humidity		Dew Point	
T°F Mean	69.3	%RH Mean	46	DP°F Mean	46.2
T°F Median	69	%RH Median	53	DP°F Median	51.7
T°F Stdev	1.2	%RH Stdev	14	DP°F Stdev	9.4
T°F Min	66.2	%RH Min	15	DP°F Min	19.3
T°F Max	79.5	%RH Max	77	DP°F Max	63.5

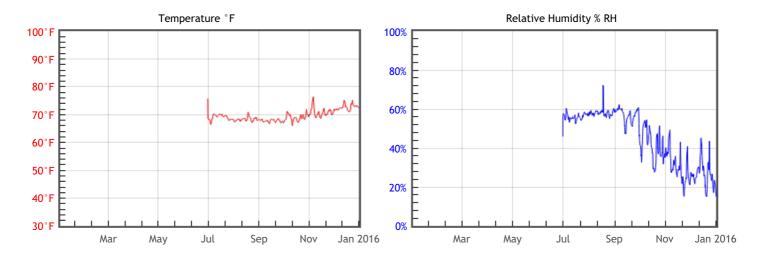
Ground West - North (WG1)

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	RISK TWPI = 41	Accelerated rate of chemical decay in all organic materials due to the cumulative effects of temperature and humidity, with especially high risk for fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics.
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 1.48 % EMC min = 5.5 % EMC max = 10.8	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	RISK % EMC max = 10.8	Heightened risk of metal corrosion due to extended periods of high levels of humidity.

Graphs



Temperature		Relative Humidity		Dew Point	
T°F Mean	69.6	%RH Mean	45	DP°F Mean	45.9
T°F Median	69	%RH Median	52	DP°F Median	50.9
T°F Stdev	1.9	%RH Stdev	14	DP°F Stdev	8.5
T°F Min	65.6	%RH Min	15	DP°F Min	20.3
T°F Max	76.4	%RH Max	72	DP°F Max	61.5

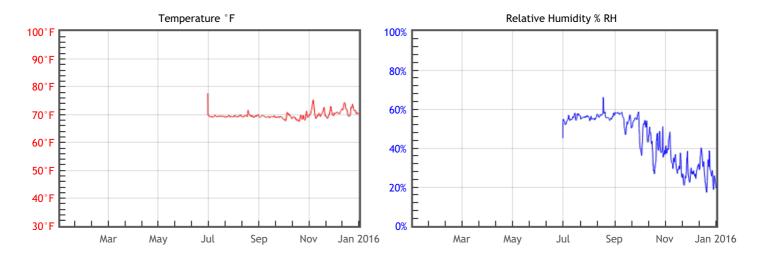
Ground West - West (WG7)

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	RISK TWPI = 40	Accelerated rate of chemical decay in all organic materials due to the cumulative effects of temperature and humidity, with especially high risk for fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics.
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 1.29 % EMC min = 5.8 % EMC max = 10.4	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 10.4	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs



Temperature		Relative H	Relative Humidity		Dew Point	
T°F Mean	69.8	%RH Mean	45	DP°F Mean	46.4	
T°F Median	69.5	%RH Median	51	DP°F Median	50.8	
T°F Stdev	1.2	%RH Stdev	12	DP°F Stdev	8	
T°F Min	67.5	%RH Min	16	DP°F Min	21.4	
T°F Max	77.7	%RH Max	68	DP°F Max	60.8	